Appln. No. 10/709,175 Docket No. 146442/GEM-0120

## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

## Listing of Claims:

- 1. (currently amended) An electronic assembly comprising:
- a first layer having a first interface surface and a plurality of cavities formed in the first interface surface;
- a second layer having a second interface surface and a plurality of electrically conductive projections disposed at the second interface surface, wherein the plurality of projections are aligned with and disposed at the plurality of cavities, the second layer comprising a diode array having a plurality of backlit photodiodes in electrical communication with the plurality of projections; and

an electrically conductive connecting material disposed at the plurality of cavities such that the connecting material non-separably connects the plurality of projections to the respective plurality of cavities, each of the plurality of cavities being configured to constrain the connecting material disposed thereat:

wherein the plurality of cavities are formed having a depth d in the first interface surface;

wherein the first interface surface is disposed apart from the second interface surface by a gap g; and

wherein the plurality of projections have a length h that is equal to or less than the sum of the depth d and the gap g, such that the connecting material bridges the distance defined by (d+g-h).

2. (canceled)

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- 3. (original) The assembly of Claim 1, wherein: the plurality of projections have a width w equal to or greater than about 100 microns and equal to or less than about 700 microns.
  - 4. (original) The assembly of Claim 3, wherein: the plurality of projections have a width w equal to about 500 microns.
- 5. (original) The assembly of Claim 3, wherein:
  the pitch of the plurality of projections is equal to or greater than about 1.1 times
  the width w and equal to or less than about 3 times the width w.
  - 6. (original) The assembly of Claim 5, wherein: the pitch of the plurality of projections is equal to about 2 times the width w.
- 7. (original) The assembly of Claim 1, wherein:
  the plurality of projections are shaped to mirror the shape of the plurality of cavities.
  - 8. (currently amended) The assembly of Claim 1, wherein:
    the first layer comprises a ceramic substrate;
    the second layer comprises a diode array having a plurality of backlit photodiodes

in electrical communication with the plurality of projections; and the connecting material comprises a conductive epoxy, a conductive solder, or any

- combination comprising at least one of the foregoing materials.
  - 9. (canceled)
- 10. (original) The assembly of Claim 9, wherein adjacent projections are absent direct electrical communication.

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- 11. (original) The assembly of Claim 8, wherein: the assembly comprises a light detector for use in medical diagnostic equipment.
- 12. (original) The assembly of Claim 8, wherein: the plurality of photodiodes are spaced on the first layer with an edge spacing equal to or less than about 100 micrometers.
- 13. (original) The assembly of Claim 12, wherein: the plurality of photodiodes are spaced on the first layer with an edge spacing equal to or less than about 25 micrometers.
- 14. (original) The assembly of Claim 13, wherein: the plurality of photodiodes are spaced on the first layer with an edge spacing equal to about 10 micrometers.
  - 15-34. (canceled)
  - An electronic assembly comprising: 35. (currently amended)
  - a first layer having a plurality of eavities pockets;
- a second layer comprising a diode array having a plurality of backlit photodiodes in electrical communication with the having a plurality of projections, wherein the plurality of projections are aligned with and disposed at the plurality of eavities pockets with a defined distance therebetween; and

an electrically conductive connecting material disposed at the plurality of eavities pockets such that the plurality of projections are electrically and non-separably bonded to the respective plurality of envities pockets via the electrically conductive connecting material;

wherein the conductive connecting material bridges the defined distance; and

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wherein each of the plurality of pockets are configured to constrain the connecting material disposed thereat.